

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
Patent Application

Inventor(s): Frank Kuo

Group Art Unit:

Filed: 02/27/04

Examiner:

Application No.: Not yet assigned

Title: ENCAPSULATION METHOD AND LEADFRAME FOR LEADLESS SEMICONDUCTOR PACKAGES

Form 1449

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
PO	A	5,645,864	07/08/97	Higuchi	425	116	04/25/96
	B	6,319,450	11/20/01	Chua et al.	264	272.17	07/12/99
	C	5,052,907	10/01/91	Matumoto et al.	425	116	07/03/90
	D	6,214,273	04/10/01	Liang et al.	264	272.14	11/10/98
	E	5,672,550	09/30/97	Tsuji et al.	437	219	01/10/96
AD	F	4,900,501	02/13/90	Saeki et al.	264	272.17	10/30/86

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
PO	G	JP2000031180A	01/28/00	JPO	H01L021	56	Yes	No
AD	H	JP358128745A	08/01/83	JPO	H01L021	56	Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	I	
Examiner	Date Considered	
AD	3/2006	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered.
Include copy of this form with next communication to applicant.